



Material Content Data Sheet



Sales Product Name		SN7002W H6327		Issued		20. July 2018			
MA#		MA001233628							
Package		PG-SOT323-3-2		Weight*		6.17 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.002	0.03		335		
	noble metal	gold	7440-57-5	0.008	0.13		1300		
	inorganic material	silicon	7440-21-3	0.091	1.47	1.63	14733	16368	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86		
	non noble metal	titanium	7440-32-6	0.003	0.04		431		
	non noble metal	chromium	7440-47-3	0.008	0.13		1293		
	non noble metal	copper	7440-50-8	2.647	42.92	43.10	429207	431017	
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	872	872	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.50		4950		
	plastics	epoxy resin	-	0.656	10.64		106434		
	inorganic material	silicondioxide	60676-86-0	2.366	38.37	49.51	383658	495042	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.15	2.15	21516	21516	
plating	noble metal	silver	7440-22-4	0.217	3.52	3.52	35185	35185	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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